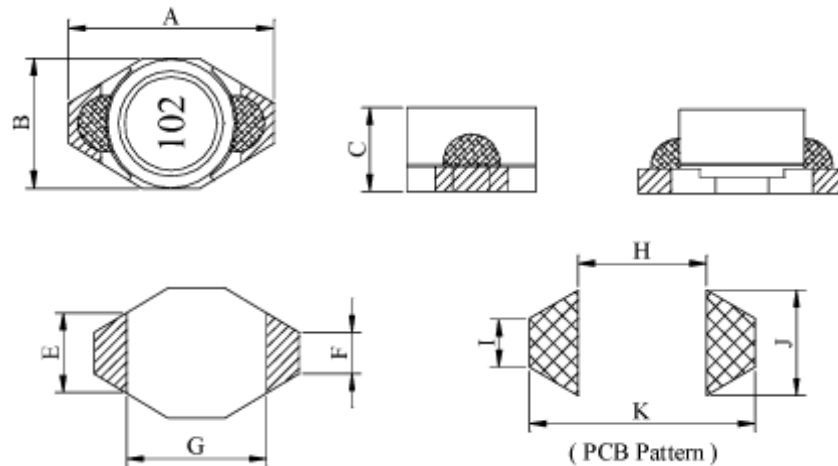


1. Configuration & Dimensions



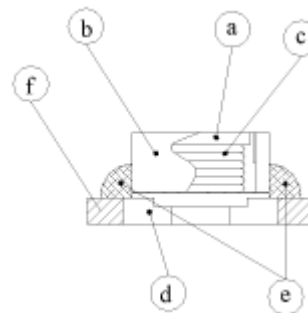
Series	Dimensions [mm]									
	A	B(max.)	C	E(ref.)	F(ref.)	G(ref.)	H(ref.)	I(ref.)	J(ref.)	K(ref.)
PS1608	6.50±0.2	4.40	2.90±0.15	2.50	1.24	4.45	4.10	1.60	3.00	7.00
PS4530	6.50±0.2	4.40	3.05 max.	2.50	1.24	4.45	4.10	1.60	3.00	7.00

2. Schematic Diagram



3. Materials

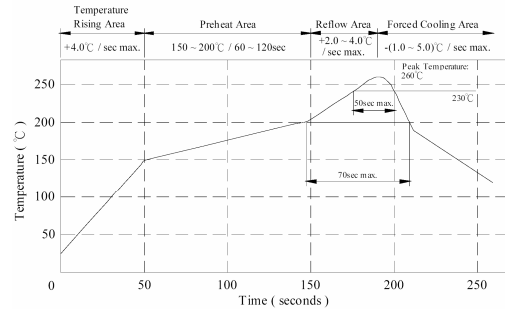
- a.- Core : Ferrite DR core
- b.- Core : Ferrite RI core
- c.- Wire : Enamelled copper wire (class F)
- d.- Base : Ceramic
- e.- Adhesive : Epoxy resin
- f.- Terminal : Mo / Mn / Ni / Au
- g.- Remark : Lead content 200ppm max. include ferrite



4. General Specification

- a.- Temp. rise : 30°C max.
- b.- Storage temp. : -40°C ~ +125°C
- c.- Operating temp. : -40°C ~ +105°C
- d.- Resistance to solder heat : 260°C. 10 secs

Peak Temp : 260°C max.
 Max time above 230°C : 50sec max.
 Max time above 200°C : 70sec max.



5. Electrical Characteristics

PS1608 (1μH - 10000μH)

DWG No.	Inductance (μH)	Q min.	Test Freq.		SRF (MHz) nom.	RDC (Ω) max.	I _{rms} (A) max.	I _{sat} (A) typ.
			L (KHz)	Q (KHz)				
PS1608 - 1R0M	1.0±20%	10	100	500	250	0.040	3.000	1.200
PS1608 - 1R5M	1.5±20%	20	100	500	125	0.045	2.800	0.920
PS1608 - 2R2M	2.2±20%	25	100	500	120	0.050	1.800	0.800
PS1608 - 3R3M	3.3±20%	40	100	200	120	0.055	1.600	0.620
PS1608 - 4R7M	4.7±20%	40	100	200	105	0.060	1.400	0.500
PS1608 - 6R8M	6.8±20%	40	100	200	50	0.065	1.200	0.400
PS1608 - 100M	10.0±20%	40	100	200	38	0.075	1.000	0.320
PS1608 - 150M	15.0±20%	40	100	100	33	0.090	0.800	0.260
PS1608 - 220M	22.0±20%	40	100	100	25	0.110	0.700	0.240
PS1608 - 330M	33.0±20%	40	100	100	20	0.190	0.600	0.160
PS1608 - 470M	47.0±20%	40	100	100	20	0.230	0.500	0.140
PS1608 - 680M	68.0±20%	40	100	100	15	0.290	0.400	0.120
PS1608 - 101M	100.0±20%	40	100	100	10	0.480	0.300	0.100
PS1608 - 151M	150.0±20%	40	100	100	9	0.590	0.260	0.080
PS1608 - 221M	220.0±20%	40	100	100	6	0.770	0.220	0.070
PS1608 - 331M	330.0±20%	40	100	100	5	1.400	0.200	0.050
PS1608 - 471M	470.0±20%	40	100	100	4	1.800	0.190	0.045
PS1608 - 681M	680.0±20%	40	100	100	3	2.200	0.180	0.040
PS1608 - 102M	1000.0±20%	40	100	100	2	3.400	0.150	0.028
PS1608 - 152M	1500.0±20%	50	100	100	2	4.200	0.120	0.024
PS1608 - 222M	2200.0±20%	50	100	100	2	8.500	0.100	0.020

PS1608 (1 μ H - 10000 μ H)

PS1608 - 332M	3300.0 \pm 20%	50	100	100	1	11.000	0.080	0.018
PS1608 - 472M	4700.0 \pm 20%	50	100	100	1	13.900	0.060	0.014
PS1608 - 682M	6800.0 \pm 20%	50	100	100	1	25.000	0.040	0.012
PS1608 - 103M	10000.0 \pm 20%	50	100	100	0.8	32.800	0.020	0.010

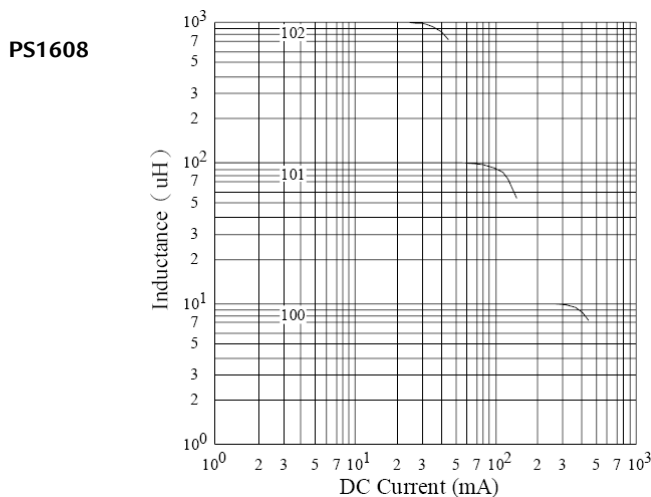
PS4530 (1000 μ H - 10000 μ H)

DWG No.	Inductance (μ H)	Q min.	Test Freq. L (KHz)	Insulation (M Ω) Core - Winding	SRF (MHz) typ.	RDC (Ω) max.	IDC (mA) max.
PS4530 - 102M	1000 \pm 20%	50	100	> 10	2.0	9	100
PS4530 - 152M	1500 \pm 20%	50	100	> 10	1.0	11	80
PS4530 - 222M	2200 \pm 20%	50	100	> 10	1.0	19	50
PS4530 - 332M	3300 \pm 20%	50	100	> 10	1.0	24	40
PS4530 - 472M	4700 \pm 20%	50	100	> 10	1.0	30	30
PS4530 - 682M	6800 \pm 20%	50	100	> 10	0.9	56	20
PS4530 - 103M	10000 \pm 20%	50	100	> 10	0.8	74	10

[Inductance tested at 0.1V] [I_{rms} base on temp. rise 30°C] [I_{sat} base on $\Delta L/L_0A = 10\%$] [Electrical Specifications at 25°C]

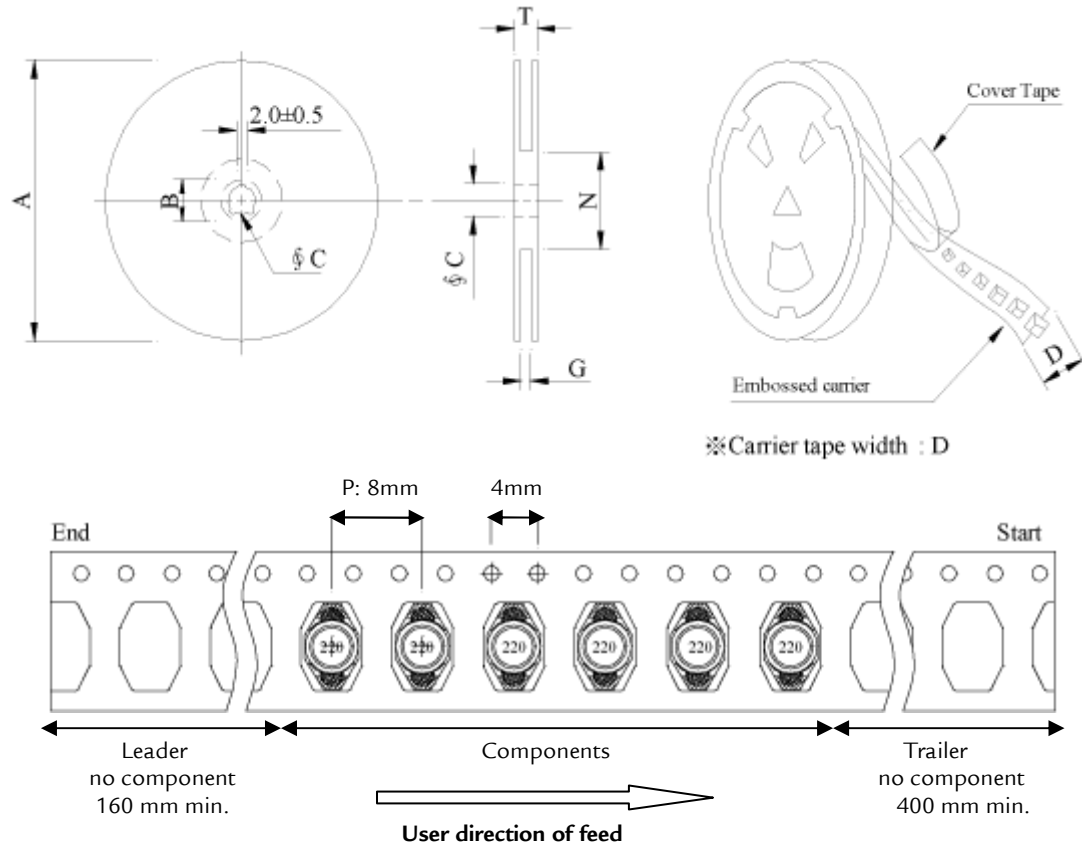
6. Curve

Inductance VS. DC Current Curve



C/Severo Ochoa 33 - Parque Tecnológico de Andalucía. 29590 Campanillas .Málaga (Spain) Phone +34 951 231 320 Fax +34 951 231 321
E-mail: mar.villarrubia@grupopremo.com Web <http://www.grupopremo.com>

7. Packaging Information



PS1608

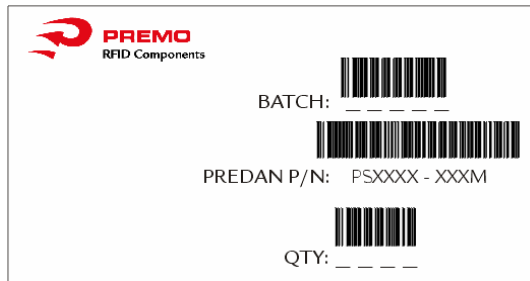
Style	Dimensions [mm]						
	A	B	C	D	G	N	T
07 - 12	178	21±0.8	13	12	14 ⁺⁰	50 ⁰	16.5
13 - 12	330	21±0.8	13±0.5	12	14 ⁺⁰	50 ⁰	18.4

PS4530

Style	Dimensions [mm]						
	A	B	C	D	G	N	T
07 - 12	178	21±0.8	13	12	14 ⁺⁰	50 ⁰	16.5

Series	Inner : Reel			Outer : Carton		
	Q'TY(pcs)	G.W.(gw)	Style	Q'TY(pcs)	G.W.(Kg)	Size(cm)
PS1608	600	250	07 - 12	24,000	10.5	42 x 41 x 24
PS1608	2,500	1,050	13 - 12	20,000	8.5	40 x 40 x 24
PS4530	600	250	07 - 12	24,000	8.0	42 x 41 x 24

8. Labelling



9. Reliability Test

Test item	Specification	Test condition															
Solderability	More than 90% of the terminal electrode shall be covered with fresh solder	Preheat : 150±25% for 60 seconds Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent Solder temp. : 235±5°C (PS1608) 260±5°C (PS4530) Flux : Rosin Dip time : 4±1 seconds															
Thermal shock test (Temp. cycle)	Inductance shall not change more than ±30%	<table border="0"> <tr> <td>Room temp.</td> <td>→</td> <td>-25±2°C</td> </tr> <tr> <td>15 minutes</td> <td></td> <td>30 minutes</td> </tr> <tr> <td colspan="3"> </td> </tr> <tr> <td>Room temp.</td> <td>→</td> <td>85±2°C</td> </tr> <tr> <td>15 minutes</td> <td></td> <td>30 minutes</td> </tr> </table> Total : 50 cycles	Room temp.	→	-25±2°C	15 minutes		30 minutes				Room temp.	→	85±2°C	15 minutes		30 minutes
Room temp.		→	-25±2°C														
15 minutes			30 minutes														
Room temp.	→	85±2°C															
15 minutes		30 minutes															
Humidity Resistance test	Temperature : 40±2°C Humidity : 90 ~ 95% Applied current : Per specifications Time : 500 hours																
High temp. Resistance test	Temperature : 105±2°C Applied current : Per specifications Time : 500 hours																

10. Edition Control

Edition	Date	Change description	Made by
1 st	31/08/06	Update Specification	Pablo Pozo

